

Reliability Challenges with 3D Integration of Semiconductor Packaging



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Abstract:

Process technology scaling has driven the need for advancement in semiconductor packaging technology to address insatiable demand in performance, power and formfactor. A growing number of innovative 3D package assembly technologies have evolved to enable the semiconductor industry to maximize their products functionality. This tutorial will cover the history on packaging development with the focus on the advent of 3D integrations. In-depth reliability studies of these 3D integration of packaging technologies will be discussed along with some general industry perspective on future roadmaps.

Biography:

Mohammad Kabir is a Technologist in Logic Technology Development Quality and Reliability group at Intel. He received his Ph.D. in Aeronautics and Astronautics from Purdue University in 2010. Since then, he has been involved in developing thermo-mechanically and environmentally reliable products at Intel.